



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-24
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
HSP053-4M5	8K61*V4U6EB1	A	CA2A	2016-06-24
Amount		UoM	Unit type	ST ECOPACK Grade
1.06		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
QFN	1,30;0.8;0.38	5	flat
Comment	Package: DFN.13.08.04-050-5L		

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8K61*V4U6E81					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.028	mg	supplier	die	Silicon (Si)	7440-21-3		0.020	mg	714286	18868
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	250000	6604
				supplier	Passivation	Silicon Oxide	7631-86-9		0.001	mg	35714	943
Leadframe	Copper & its alloys	0.777	mg	supplier	alloy	Copper (Cu)	7440-50-8		0.717	mg	922780	676415
				supplier	alloy	Nickel (Ni)	7440-02-0		0.023	mg	29601	21698
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.001	mg	1287	943
				supplier	alloy	Silicon (Si)	7440-21-3		0.005	mg	6435	4717
				supplier	metallization	Nickel (Ni)	7440-02-0		0.019	mg	24453	17925
				supplier	metallization	Palladium (Pd)	7440-05-3		0.009	mg	11583	8491
Die attach	Other Organic Materials	0.051	mg	supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	3861	2830
				supplier	glue or tape	Silver(Ag)	7440-22-4		0.043	mg	843138	40566
				supplier	glue or tape	Amine Polymer	28630-26-4		0.004	mg	78431	3774
				supplier	glue or tape	Epoxy resin a	25068-38-6		0.004	mg	78431	3774
Bonding wires	Other inorganic materials	0.013	mg	supplier	wire	Gold (Au)	7440-57-5		0.013	mg	1000000	12264
Encapsulation	Other Organic Materials	0.191	mg	supplier	mold compound	Silica, vitreous	60676-86-0		0.148	mg	774869	139623
				supplier	mold compound	Silica	7631-86-9		0.020	mg	104712	18868
				supplier	mold compound	Quartz	14808-60-7		0.001	mg	5236	943
				supplier	mold compound	Epoxy Resin	85954-11-6		0.011	mg	57592	10377
				supplier	mold compound	Epoxyde Bisphenol A Resin	25068-38-6		0.002	mg	10527	1887
				supplier	mold compound	Phenol Resin	26834-02-6		0.008	mg	41885	7547
				supplier	mold compound	Carbon black	1333-86-4		0.001	mg	5236	943